





# The Silicon Microstrip Tracker for the Mini.PAN experiment

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#### Mini.PAN Project TRACKER goals

- Validate a novel cosmic ray measurement instrument concept
  - Develop a fine pitch silicon strip detector for the advanced option of the Strip X Detector
  - Design and produce large pitch Strip Y detector
  - Design and produce low noise and low power ASIC chips for Strip X detectors
  - Develop ASIC chips for Strip Y detectors, with large dynamic range, multi-range
  - readout, trigger output and good time resolution
  - Design, produce and space qualify tracker modules

# Mini.PAN Silicon TRACKER

- Three Tracker Modules. Each module made of:
- Two Strip-X detectors with 25µm readout pitch, providing a 2µm spatial resolution, read-out by 32 IDEAS VA1140  $\rightarrow$  2048 readout channels
- One Strip-Y detector with 400µm readout pitch, providing 115µm spatial resolution read-out by one high dynamic range VATA GT7.2 chip  $\rightarrow$  128 readout channels



## **Detector Construction Steps:**

Alignment of PCB on a precise jig



- Thin silicon strip sensor: 150µm
- Pitch adapter to fan-out to bonding pads directly implemented on the silicon wafer with double metal layer
- Low noise ASIC and analog readout
- Robust module design and assembly
- Thermal/mechanical system that ensures stability during operation
- Tracker power consumption 8W

# **PAN Silicon sensors characteristics**

Device type	Single side AC-readout /double metal
Silicon Type	N-type, Phosphorus doped
Crystal orientation	<100>
Chip thickness	150 <b>±</b> 15 μm
Front and back side metal	AL
Full depletion voltage	Max. 50 V

### Strip X sensor properties.

X sensor overall size	59000±20 μm x 59000±20 μm
Active area	51200 μm x 51200 μm
Number of Strips	2048
Strip pitch	25 μm
Strip width	13 µm
Readout AL width	10 µm
Readout PAD pitch	96 μm

#### Strip Y sensor properties.

Y sensor overall size	59000±20 μm x 59000±20 μm
Active area	Circular with D=51200 μm
Number of Strips	128
Strip pitch	400 μm
Strip width	380 μm
Readout AL width	10 μm
Readout PAD pitch	91.2(2lines) μm



# Dispensing of conductive glue EJ2189 and structural glue DC3145 grey

- Placement of silicon sensor on PCB and curing
- Wire bonding of sensors with the VA1140, respectively VATAGP7.2
- Qualification: electrical and mechanical test
- Integration of Strip-X and Strip-Y detectors in Tracker Modules
- Integration of Modules in Tracker
- **Beam Tests and Space Qualifification**
- 8 Strip-X detectors and 3 Strip-Y detectors already built



Strip Y detector readout by a VATAGP 7.2



Ultrasonic wire bonding with a M17L F&K Delvotec machine



Strip X detector calibration: standard deviation of ADC values per channel from a calibration run (CN subtracted): ~1.5-2.5 ADC units





#### **Space Qualification – Mechanical Tests**

A Mechanical Tracker Module was built for space qualification with dummy X and Y sensors, respectively



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